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FEATURES

Keeps track of hundredths of seconds, seconds, minutes, hours, days, date of the month, months, and years

Converts standard 2k x 8 up to 512k x 8 CMOS static RAMs into nonvolatile memory

Embedded lithium energy cell maintains watch information and retains RAM data

Watch function is transparent to RAM operation

Month and year determine the number of days in each month; leap year compensation valid up to 2100

Lithium energy source is electrically disconnected to retain freshness until power is applied for the first time

Proven gas–tight socket contacts

Full ±10% operating range

Operating temperature range 0°C to 70°C

Accuracy is better than ±1 minute/month @ 25°C

ORDERING INFORMATION (5V)

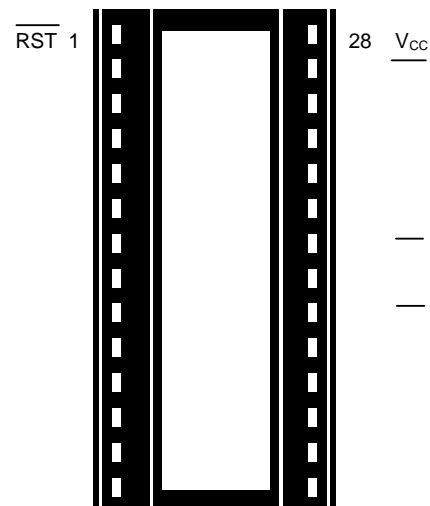DS1216B, DS1216C, DS1216D, DS1216H

ORDERING INFORMATION (3.3V)

DS1216B-3.3V, DS1216C-3.3V, DS1216D-3.3V, DS1216H-3.3V

PIN DESCRIPTION DS1216B & DS1216C

Pin 1	$\overline{RST}$	- $\overline{RESET}$
Pin 11	DQ0	- Data Input/Output 0
Pin 14	GND	- Ground
Pin 20	$\overline{CE}$	- Conditioned Chip Enable
Pin 22	$\overline{OE}$	- Output Enable
Pin 27	$\overline{WE}$	- Write Enable
Pin 28	V_{CC}	- Switched V_{CC}

(DS1216B only)

Pin 26	Vcc	- Switched Vcc for 24-pin RAM

$\overline{RST}$ 1   28 V_{CC}
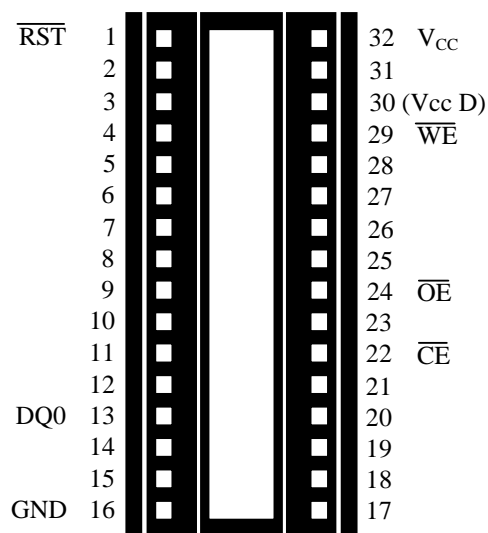
28-Pin Intelligent Socket

082500

PIN DESCRIPTION FOR DS1216D AND DS1216H

All pins pass through except 22 and 32.

Pin 1	$\overline{\text{RST}}$	-	RESET
Pin 13	DQ0	-	Data Input/Output
Pin 16	GND	-	Ground
Pin 22	$\overline{\text{CE}}$	-	Conditioned Chip Enable
Pin 24	$\overline{\text{OE}}$	-	Output Enable
Pin 29	$\overline{\text{WE}}$	-	Write Enable
Pin 32	V_{CC}	-	Switched V_{CC} for 32-pin RAM

(DS1216D only)
(Pin 30 Vcc - Switched Vcc for 28-Pin RAM)

32-Pin Intelligent Socket

DESCRIPTION

The DS1216 SmartWatch/RAM Sockets are 600-mil wide DIP sockets with a built–in CMOS watch function, a nonvolatile RAM controller circuit, and an embedded lithium energy source. The sockets provide a NV RAM solution for memory sized from 2k x8 to 512k x8 with package sizes from 26 pin to 32 pins. When a socket is mated with a CMOS SRAM, it provides a complete solution to problems associated with memory volatility and uses a common energy source to maintain time and date. A key feature of the SmartWatch is that the watch function remains transparent to the RAM. The SmartWatch monitors V_{CC} for an out–of–tolerance condition. When such a condition occurs, an internal lithium energy source is automatically switched on and write protection is unconditionally enabled to prevent loss of watch and RAM data.

Using the SmartWatch saves PC board space since the combination of SmartWatch and the mated RAM take up no more area than the memory alone. The SmartWatch uses the Vcc, Data I/O 0, $\overline{\text{CE}}$, $\overline{\text{OE}}$, and WE for RAM and watch control. All other pins are passed straight through to the socket receptacle.

The SmartWatch provides timekeeping information including hundredths of seconds, seconds, minutes, hours, day, date, month, and year information. The date at the end of the month is automatically adjusted for months with less than 31 days, including correction for leap years. The SmartWatch operates in either 24–hour or 12–hour format with an AM/PM indicator.
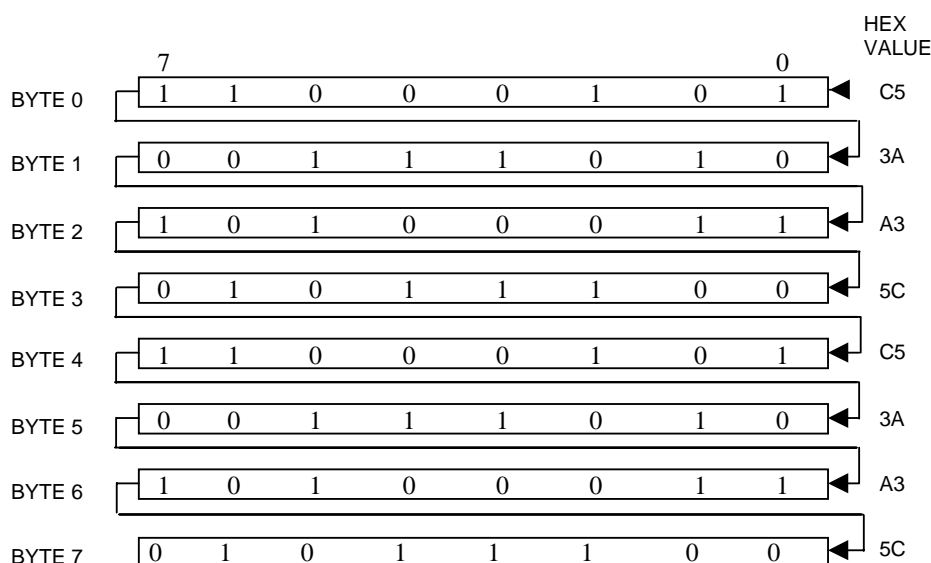
OPERATION

Communication with the SmartWatch is established by pattern recognition on a serial bit stream of 64 bits which must be matched by executing 64 consecutive write cycles containing the proper data on DQ0. All accesses which occur prior to recognition of the 64–bit pattern are directed to memory.

After recognition is established, the next 64 read or write cycles either extract or update data in the SmartWatch, and memory access is inhibited.

Data transfer to and from the timekeeping function is accomplished with a serial bit stream under control of Chip Enable ($\overline{CE}$), Output Enable ($\overline{OE}$), and Write Enable ($\overline{WE}$). Initially, a read cycle to any memory location using the $\overline{CE}$ and $\overline{OE}$ control of the SmartWatch starts the pattern recognition sequence by moving a pointer to the first bit of the 64–bit comparison register. Next, 64 consecutive write cycles are executed using the $\overline{CE}$ and $\overline{WE}$ control of the SmartWatch. These 64 write cycles are used only to gain access to the SmartWatch. Therefore, any address to the memory in the socket is acceptable. However, the write cycles generated to gain access to the SmartWatch are also writing data to a location in the mated RAM. The preferred way to manage this requirement is to set aside just one address location in RAM as a SmartWatch scratch pad. When the first write cycle is executed, it is compared to bit 0 of the 64–bit comparison register. If a match is found, the pointer increments to the next location of the comparison register and awaits the next write cycle. If a match is not found, the pointer does not advance and all subsequent write cycles are ignored. If a read cycle occurs at any time during pattern recognition, the present sequence is aborted and the comparison register pointer is reset. Pattern recognition continues for a total of 64 write cycles as described above until all the bits in the comparison register have been matched (this bit pattern is shown in Figure 1). With a correct match for 64 bits, the SmartWatch is enabled and data transfer to or from the timekeeping registers can proceed. The next 64 cycles will cause the SmartWatch to either receive or transmit data on DQ0, depending on the level of the $\overline{OE}$ pin or the $\overline{WE}$ pin. Cycles to other locations outside the memory block can be interleaved with $\overline{CE}$ cycles without interrupting the pattern recognition sequence or data transfer sequence to the SmartWatch.

SMARTWATCH COMPARISON REGISTER DEFINITION Figure 1

	7							0	HEX VALUE
BYTE 0	1	1	0	0	0	1	0	1	C5
BYTE 1	0	0	1	1	1	0	1	0	3A
BYTE 2	1	0	1	0	0	0	1	1	A3
BYTE 3	0	1	0	1	1	1	0	0	5C
BYTE 4	1	1	0	0	0	1	0	1	C5
BYTE 5	0	0	1	1	1	0	1	0	3A
BYTE 6	1	0	1	0	0	0	1	1	A3
BYTE 7	0	1	0	1	1	1	0	0	5C

NOTE:

The pattern recognition in Hex is C5, 3A, 5C, C5, 3A, A3, 5C. The odds of this pattern accidentally duplicating and causing inadvertent entry to the SmartWatch are less than 1 in 10^{19}. This pattern is sent to the SmartWatch LSB to MSB.

NONVOLATILE CONTROLLER OPERATION

The DS1216 SmartWatch performs circuit functions required to make a CMOS RAM nonvolatile. First, a switch is provided to direct power from the battery or V_{CC} supply, depending on which voltage is greater. This switch has a voltage drop of less than 0.2 volts. The second function which the SmartWatch provides is power–fail detection. Power–fail detection occurs at V_{TP}. The DS1216 constantly monitors the V_{CC} supply. When V_{CC} goes out of tolerance, a comparator outputs a power–fail signal to the chip enable logic. The third function accomplishes write protection by holding the chip enable signal to the memory within 0.2 volts of V_{CC} or battery. During nominal power supply conditions the memory chip enable signal will track the chip enable signal sent to the socket with a maximum propagation delay of 7 ns for the 5 volt and 12 ns for the 3.3 volt version.

FRESHNESS SEAL

Each DS1216 is shipped from Dallas Semiconductor with its lithium energy source disconnected, insuring full energy capacity. When V_{CC} is first applied at a level greater than the lithium energy source is enabled for battery backup operation.

SMARTWATCH REGISTER INFORMATION

The SmartWatch information is contained in eight registers of 8 bits, each of which is sequentially accessed one bit at a time after the 64–bit pattern recognition sequence has been completed. When updating the SmartWatch registers, each must be handled in groups of 8 bits. Writing and reading individual bits within a register could produce erroneous results. These read/ write registers are defined in Figure 2.

Data contained in the SmartWatch registers is in binary coded decimal format (BCD). Reading and writing the registers is always accomplished by stepping through all eight registers, starting with bit 0 of register 0 and ending with bit 7 of register 7.

AM–PM/12/24 MODE

Bit 7 of the hours register is defined as the 12– or 24–hour mode select bit. When high, the 12–hour mode is selected. In the 12–hour mode, bit 5 is the AM/PM bit with logic high being PM. In the 24–hour mode, bit 5 is the second 10–hour bit (20–23 hours).

OSCILLATOR AND RESET BITS

Bits 4 and 5 of the day register are used to control the $\overline{\text{RESET}}$ and oscillator functions. Bit 4 controls the $\overline{\text{RESET}}$ (pin 1). When the $\overline{\text{RESET}}$ bit is set to logic 1, the $\overline{\text{RESET}}$ input pin is ignored. When the $\overline{\text{RESET}}$ bit is set to logic 0, a low input on the $\overline{\text{RESET}}$ pin will cause the SmartWatch to abort data transfer without changing data in the watch registers. Bit 5 controls the oscillator. When set to logic 1, the oscillator is off. When set to logic 0, the oscillator turns on and the watch becomes operational. These bits are shipped from the factory set to logic 1.
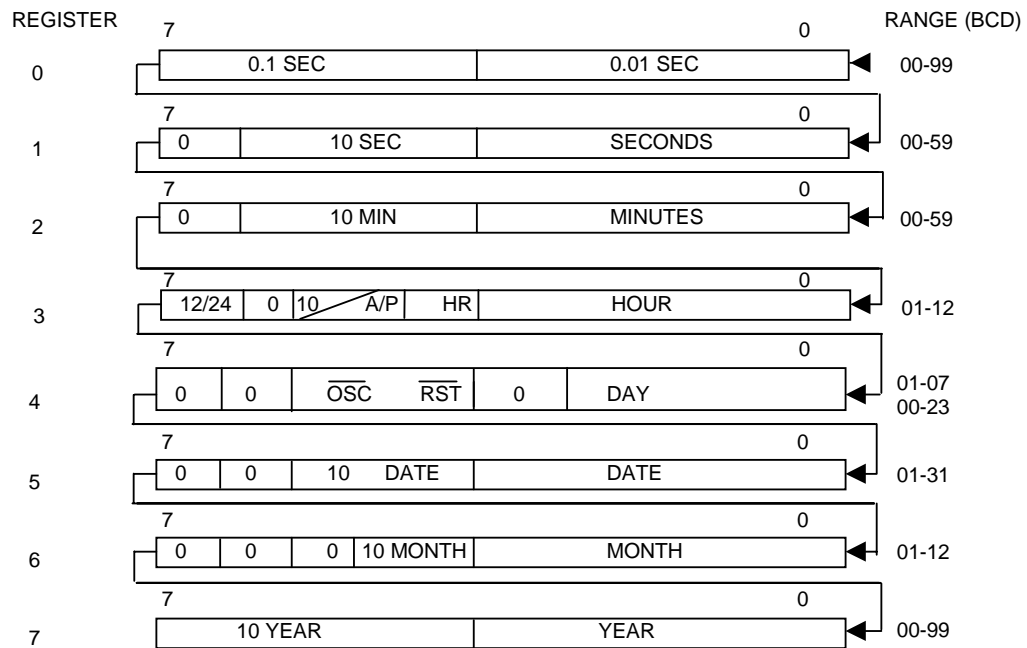
ZERO BITS

Registers 1,2,3,4,5, and 6 contain one or more bits which will always read logic 0. When writing these locations, either a logic 1 or 0 is acceptable.

ADDITIONAL INFORMATION

Please see Application Notes 4 and 52 for information regarding optional modifications and utilization of the Phantom Clock contained within the SmartWatch.

SMARTWATCH REGISTER DEFINITION Figure 2

REGISTER	7 ... 0	RANGE (BCD)
0	0.1 SEC / 0.01 SEC	00-99
1	0 / 10 SEC / SECONDS	00-59
2	0 / 10 MIN / MINUTES	00-59
3	12/24 / 0 / 10 / A/P / HR / HOUR	01-12
4	0 / 0 / OSC / RST / 0 / DAY	01-07 00-23
5	0 / 0 / 10 DATE / DATE	01-31
6	0 / 0 / 0 / 10 MONTH / MONTH	01-12
7	10 YEAR / YEAR	00-99

ABSOLUTE MAXIMUM RATINGS*

Voltage on any Pin Relative to Ground	–0.3V to +7.0V for 5V
Voltage on any Pin Relative to Ground	–0.3V to +3.6V for 3.3V
Operating Temperature	0°C to 70°C
Storage Temperature	–40°C to +70°C
Soldering Temperature	See J-STD-020A specification (See Note 6)

* This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operation sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS   (0°C to 70°C)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Vcc pin 5V Supply	V_{CC}	4.5	5.0	5.5	V	1, 3
Vcc pin 3 V Supply	Vcc	3.0	3.3	3.6	V	1,3
Logic 1	V_{IH}	2.2		$V_{CC} + 0.3$	V	1, 10
Logic 0	V_{IL}	-0.3		+0.8	V	1, 10

DC ELECTRICAL CHARACTERISTICS-5V   (0°C to 70°C; $V_{CC} = 5.0 \pm 10\%$)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Vcc Supply	I_{CCI}			5	mA	3, 4,5
Vcc Supply Voltage	V_{CCO}	$V_{CC} - 0.2$			V	3, 8
Vcc Supply Current	I_{CCO}			80	mA	3, 8
Input Leakage	I_{IL}	-1.0		+1.0	μA	4,10,13
Output @ 2.4V	I_{OH}	-1.0			mA	2
Output @ 0.4V	I_{OL}			4.0	mA	2
Write Protection Voltage 5V Vcc	V_{TP}	4.25		4.5	V	

DC ELECTRICAL CHARACTERISTICS-3.3V   (0°C to 70°C; V_{CC} = 3.3 ±10%)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Vcc Supply	I_{CCI}			3.5	mA	3, 4,5
Vcc Supply Voltage	V_{CCO}	V_{CC} - 0.2			V	3, 8
Vcc Supply Current	I_{CCO}			60	mA	3, 8
Input Leakage	I_{IL}	-1.0		+1.0	µA	4,10,13
Output @ 2.4V	I_{OH}	-1.0			mA	2
Output @ 0.4V	I_{OL}			3.0	mA	2
Write Protection Voltage 5V Vcc	V_{TP}	2.8		3.0	V	

BACKUP POWER CHARACTERISTICS   (0°C to 70°C; Vcc<V_{TP})

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
CE Output	V_{OHL}	V_{BAT}-0.2			V	3
RAM Vcc pin Battery Current	I_{BAT}			RAM Stby I +1 ua	uA	3
RAM V_{CC} (Battery) Voltage	V_{BAT}	2	3	3.6	V	3,15
RAM V_{CC} (Battery) I max	Ibmax			10	uA	14
Total Battery Capacity Available	Ebat	90			mAH	14
Recovery at Power-Up	t_{REC}			2	ms	
V_{CC} Slew Rate fall	t_F	0			µs	
$\overline{CE}$ Pulse Width	t_{CE}			1.5	µs	7

CAPACITANCE ($t_A = 25°C$)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Input Capacitance	C_{IN}			5	pF	
Output Capacitance	C_{OUT}			7	pF	

AC ELECTRICAL CHARACTERISTICS (0°C to 70°C; V_{CC} = 4.5 to 5.5V)

PARAMETER	SYMBOL	MIN	TYPE	MAX	UNITS	NOTES
Read Cycle Time	t_{RC}	75			ns	
$\overline{CE}$ Access Time	t_{CO}			65	ns	
$\overline{OE}$ Access Time	t_{OE}			65	ns	
$\overline{CE}$ To Output Low Z	t_{COE}	6			ns	
$\overline{OE}$ To Output Low Z	t_{OEE}	6			ns	
$\overline{CE}$ To Output High Z	t_{OD}			30	ns	
$\overline{OE}$ To Output High Z	t_{ODO}			30	ns	
Read Recovery	t_{RR}	15			ns	
Write Cycle Time	t_{WC}	75			ns	
Write Pulse Width	t_{WP}	75			ns	
Write Recovery	t_{WR}	15			ns	11
Data Setup Time	t_{DS}	35			ns	12
Data Hold Time	t_{DH}	0			ns	12
$\overline{CE}$ Pulse Width	t_{CW}	65			ns	
$\overline{RESET}$ Pulse Width	t_{RST}	75			ns	
$\overline{CE}$ Propagation Delay	t_{PD}			6	ns	2,9
$\overline{CE}$ High to Power-Fail	t_{PF}			0	ns	

AC ELECTRICAL CHARACTERISTICS (0°C to 70°C; V_{CC} = 3.3± 10%)

| PARAMETER	SYMBOL	MIN	TYPE	MAX	UNITS	NOTES
Read Cycle Time	t_{RC}	130			ns	
$\overline{CE}$ Access Time	t_{CO}		0	110	ns	
$\overline{OE}$ Access Time	t_{OE}			110	ns	
$\overline{CE}$ To Output Low Z	t_{COE}	6			ns	
$\overline{OE}$ To Output Low Z	t_{OEE}	6			ns	
$\overline{CE}$ To Output High Z	t_{OD}			45	ns	
$\overline{OE}$ To Output High Z	t_{ODO}			45	ns	
Read Recovery	t_{RR}	25			ns	
Write Cycle Time	t_{WC}	130			ns	
Write Pulse Width	t_{WP}	110			ns	
Write Recovery	t_{WR}	25			ns	11
Data Setup Time	t_{DS}	50			ns	12
Data Hold Time	t_{DH}	0			ns	12
$\overline{CE}$ Pulse Width	t_{CW}	110			ns	
$\overline{RESET}$ Pulse Width	t_{RST}	130			ns	
$\overline{CE}$ Propagation Delay	t_{PD}			12	ns	2,9
$\overline{CE}$ High to Power-Fail	t_{PF}			0	ns	

TIMING DIAGRAM: READ CYCLE TO SMARTWATCH
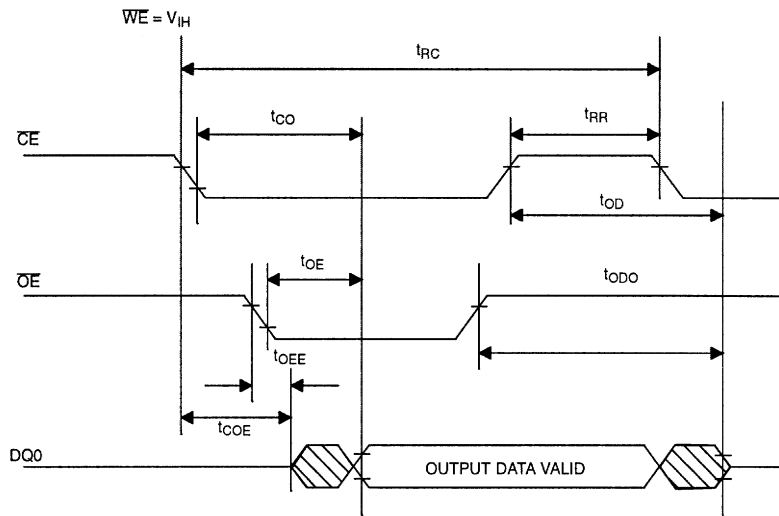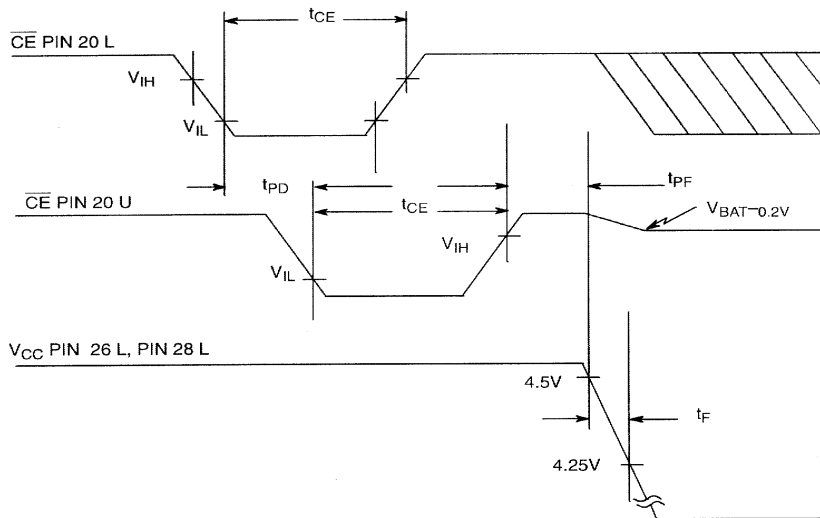

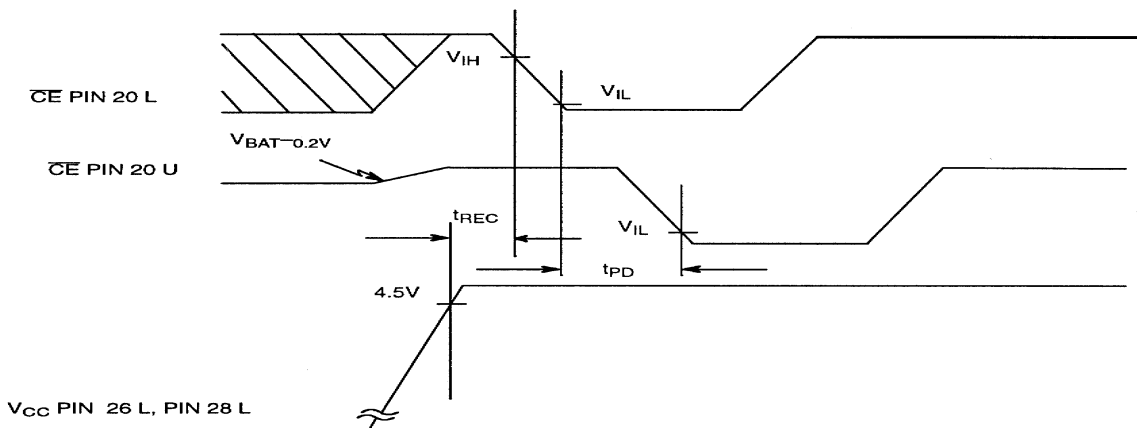# TIMING DIAGRAM: WRITE CYCLE TO SMARTWATCH
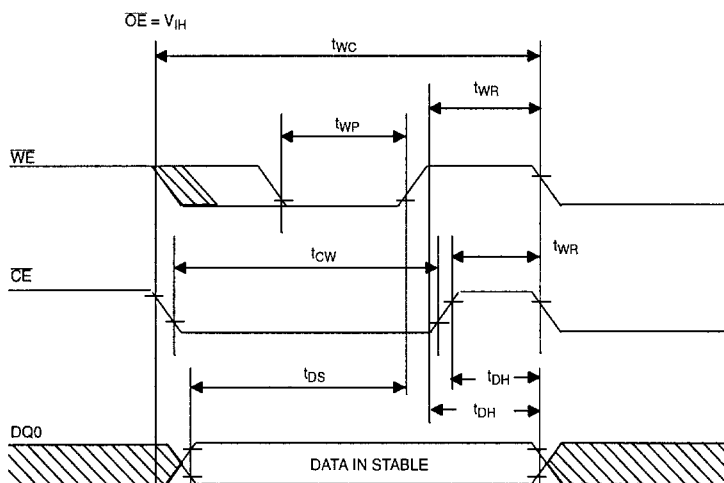
TIMING DIAGRAM: RESET FOR SMARTWATCH
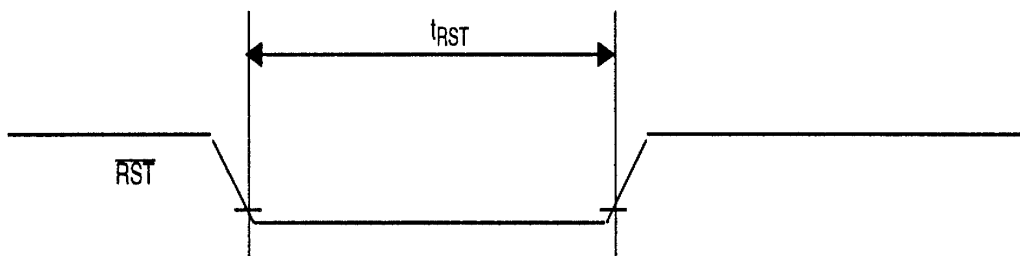
TIMING DIAGRAM: POWER-DOWN

## TIMING DIAGRAM: POWER-UP

WARNING:

Under no circumstances are negative undershoots of any amplitude allowed when device is in battery backup mode. Water washing for flux removal will discharge internal lithium source because exposed voltage pins are present.

NOTES:

1. All voltages are referenced to ground.
2. Measured with a load as shown in Figure 3.
3. Pin locations are designated "U" when a parameter definition refers to the socket receptacle and "L" when a parameter definition refers to the socket pin.
4. No memory inserted in the socket.
5. Pin 26L can be connected to V_{CC} or left disconnected at the PC board.
6. SmartWatch sockets can be successfully processed through some conventional wave–soldering techniques as long as temperature exposure to the lithium energy source contained within does not exceed +85°C. However, post solder cleaning with water washing techniques is not permissible. Discharge to the lithium energy source may result, even if de-ionized water is utilized. It is equally imperative that ultrasonic vibration is not used in order to avert damage to the quartz crystal resonator employed by the oscillator circuit.
7. t_{CE} max. must be met to ensure data integrity on power loss.
8. V_{CC} is within nominal limits and a memory is installed in the socket.
9. Input pulse rise and fall times equal 10 ns.
10. Applies to Pins 1 L, 11 L, 20 L, 22 L, and 27 L.
11. t_{WR} is a functions of the latter occurring edge of $\overline{WE}$ or $\overline{CE}$.
12. t_{DH} and t_{DS} are a function of the first occurring edge of $\overline{WE}$ or $\overline{CE}$.
13. $\overline{RST}$ (Pin 1) has an internal pull–up resistor.
14. Total battery capacity is used to determine the expected lifetime of a DS1216 in battery back mode. The user should determine the Standby Current of the selected RAM and calculate the expected lifetime. The maximum (Ibmax) current draw from the DS1216 is 10 ua.
15. The DS1216 products are shipped with backup battery power off. First power up switches backup battery on to clock and RAM Vcc pin upon power down.

OUTPUT LOAD Figure 3
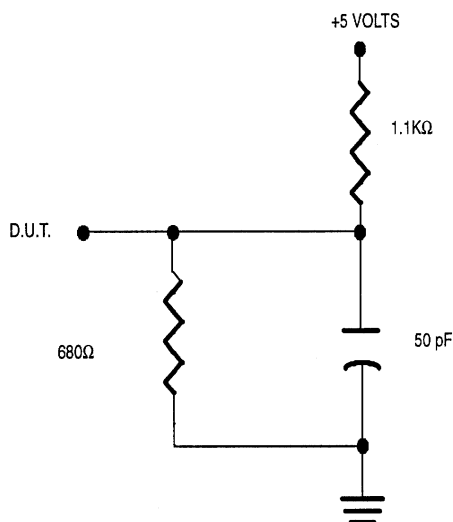
DS1216 28 SMARTWATCH
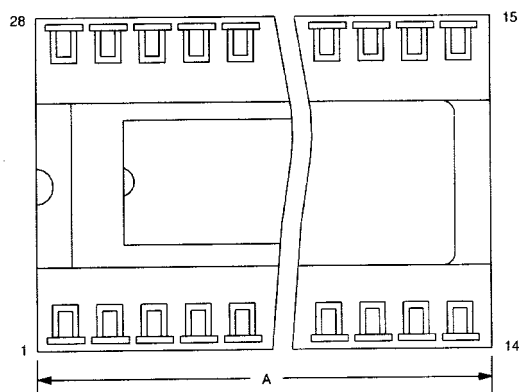
PKG	28-PIN		32-PIN	
DIM	MIN	MAX	MIN	MAX
A IN.	1.390	1.420	1.580	1.620
MM	35.31	36.07	40.13	41.14
B IN.	0.690	0.720	0.690	0.720
MM	17.53	18.29	17.53	18.29
C IN.	0.420	0.470	0.400	0.470
MM	10.67	11.94	10.16	11.94
D IN.	0.035	0.065	0.035	0.065
MM	0.89	1.65	0.89	1.65
E IN.	0.055	0.075	0.055	0.075
MM	1.39	1.90	1.39	1.90
F IN.	0.120	0.160	0.120	0.160
MM	3.04	4.06	3.04	4.06
G IN.	0.090	0.110	0.090	0.110
MM	2.29	2.79	2.29	2.79
H IN.	0.590	0.630	0.590	0.630
MM	14.99	16.00	14.99	16.00
J IN.	0.008	0.012	0.008	0.012
MM	0.20	0.30	0.20	0.30
K IN.	0.015	0.021	0.015	0.021
MM	0.38	0.53	0.38	0.53
L IN.	0.380	0.420	0.380	0.420
MM	9.65	10.67	9.65	10.67

EQUAL SPACES AT
.100 ± .010 (TNA)